


# Axiom Electronics PCBA Design for Manufacturability Guidelines

Section: 10.7	Revision: A	Revision Date: 2/14/13
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DFM Subject: Thermal Relief Connections
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<b>DFM Requirement:</b> When a pad or via connects to a solid layer (i.e. power or ground layers) the connection shall use a thermal relief design (see detail section below for an example).
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<b>DFM Impact:</b> When a pad or via connects to a solid layer (i.e. power or ground layers) without a thermal relief the solder does not fill the hole completely because heat drains away from the hole.
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<b>DFM Details: Thermal Relief Design Example</b>    Thermal Relief in a Plated Through-Hole
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